

## ABSTRACT

Present invention provides an aqueous emulsion type photosensitive resin composition which forms a cured film significantly superior in water and solvent resistances in comparison with the conventional aqueous emulsion type photosensitive resin compositions. This photosensitive resin composition contains (A) an emulsion of a photosensitive water-insoluble polymer, the emulsion being obtained by reacting (i) an aqueous polymer emulsion whose main ingredient is a water-insoluble polymer and which contains a polymer having a hydroxyl group with (ii) an N-alkylo(meth)acrylamide, (B) a compound having a photoreactive ethylenically unsaturated group, and (C) a photopolymerization initiator.